

USPAE / IPC WORKSHOP:

Bolstering U.S. IC Substrate Capabilities



May 16, 2024
Willard Hotel | Washington, DC

On May 16, USAPE and IPC will host an invitation-only workshop of government and electronics industry stakeholders on integrated circuit (IC) substrates. The workshop will further work on a U.S. Department of Defense-funded project to study and recommend approaches to addressing the country's lack of IC substrate manufacturing capabilities. The project was awarded to a USPAE/IPC team in October and a final study is due to DoD in June.

AGENDA

9:00 am Welcome

- John Mitchell, CEO, IPC
- Chris Mitchell, Interim Executive Director, USPAE

9:15 am Keynote: Molly Just

- Director, DoD's CHIPS Coordination Cell (C3)

9:45 am DoD Panel: Onshoring U.S. Substrate Fabrication for National Security

- Korine Duval, Ph.D., Microelectronics Sector Lead, Industrial Base Analysis and Sustainment (IBAS) Director
- Matt McQueen, Chief Engineer - Printed Circuit Technology, NSWCC Crane
- Jim Will, Skywater, Senior Director, A&D Business Unit
- Venky Sundaram, Founder/President, 3D System Scaling

10:30 am DoD IC Substrate Project

- Joe O'Neil, PCB Market Catalyst (PCBMC) Lead, IPC

10:45 am Break

11:00 am Defining the Challenge (Break Out Groups)

- Technology/R&D (Devan Iyer, IPC)
- Standards (Matt Kelly, IPC)
- Workforce (David Hernandez, IPC)
- Financial Competitiveness (Chris Peters, USPAAE)

12:30 pm Luncheon Keynote: Dr. George Orji

- Deputy Director, CHIPS NAPMP

1:30 pm Defining the Solutions (Break Out Groups)

- Technology/R&D (Devan Iyer, IPC)
- Standards (Matt Kelly, IPC)
- Workforce (David Hernandez, IPC)
- Financial Competitiveness (Chris Peters, USPAAE)

3:15 pm Break

3:30 pm Readout

- John Mitchell, CEO, IPC
- Joe O'Neil, PCBMC Lead, IPC

5:00 pm Next Steps

- Joe O'Neil, PCBMC Lead, IPC

5:30 pm Networking Reception